

IGBT Module

SK150GB066T

Target Data

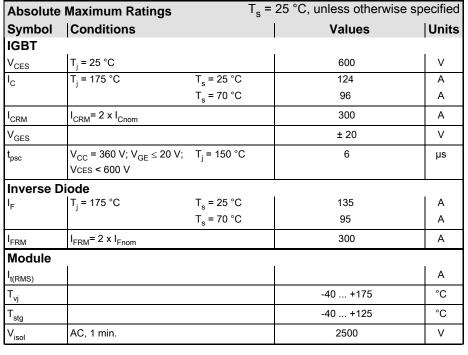
Features

- Compact design
- One scre mounting
- Heat transfer and isolation trough direct copper bonded aluminium oxide ceramic (DCB)
- Trench IGBT technology
- · CAL HD technology FWD
- Integrated NTC temperature sensor

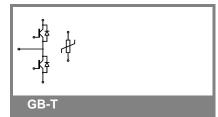
Typical Applications*

Remarks

V_{isol} = 3000V AC,50Hz,1s



Characteristics $T_s =$			25 °C, unless otherwise specified				
Symbol	Conditions		min.	typ.	max.	Units	
IGBT							
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 2.4 \text{ mA}$		5	5,8	6,5	V	
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C			0,0076	mA	
		T _j = 125 °C				mA	
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V	T _j = 25 °C			1200	nA	
		T _j = 125 °C				nA	
V _{CE0}		T _j = 25 °C		0,8	1,1	V	
		T _j = 150 °C		0,7	1	V	
r _{CE}	V _{GE} = 15 V	T _j = 25°C		4	5	mΩ	
		$T_j = 150^{\circ}C$		6,35	7	$m\Omega$	
V _{CE(sat)}	I _{Cnom} = 150 A, V _{GE} = 15 V			1,45	1,85	V	
		$T_j = 150^{\circ}C_{chiplev.}$		1,65	2,05	V	
C _{ies}				9,4		nF	
C _{oes}	V _{CE} = 25, V _{GE} = 0 V	f = 1 MHz		0,6		nF	
C _{res}				0,29		nF	
Q_G	V _{GE} = -7V+15V			1400		nC	
t _{d(on)}				95		ns	
t _r	$R_{Gon} = 8 \Omega$	V _{CC} = 300V		50		ns	
E _{on}	di/dt = 2250 A/µs	I _C = 150A		6,25		mJ	
t _{d(off)}	$R_{Goff} = 8 \Omega$ di/dt = 2250 A/µs	T _j = 150 °C		541 70		ns	
t _f E _{off}	ui/ut – 2250 A/µS	V _{GE} = -7/+15 V		70 5,7		ns mJ	
R _{th(j-s)}	per IGBT	<u>l</u>		0,65		K/W	





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Characteristics									
Symbol	Conditions		min.	typ.	max.	Units			
Inverse Diode									
$V_F = V_{EC}$	I _{Fnom} = 150 A; V _{GE} = 0 V			1,35		V			
		$T_j = 150 ^{\circ}C_{chiplev.}$		1,31		V			
V_{F0}		T _j = 25 °C				V			
		T _j = 150 °C		0,85		V			
r _F		T _j = 25 °C				mΩ			
		T _j = 150 °C		3,9		$m\Omega$			
I _{RRM}	I _F = 150 A	T _i = 150 °C		100		Α			
Q_{rr}	di/dt = 2250 A/µs	,		11		μC			
E _{rr}	V _{CC} = 300V			1,7		mJ			
R _{th(j-s)D}	per diode			0,73		K/W			
M _s	to heat sink		2,5		2,75	Nm			
w				60		g			
Temperature sensor									
R ₁₀₀	$T_s = 100^{\circ}C (R_{25} = 5k\Omega)$		•	493±5%		Ω			

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

